Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing) and dummy with (opening cavity window hole trench slot groove pocket)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:29
L2	177	(insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing) and dummy with (opening cavity window hole trench slot groove pocket)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:46
L7	187	acoustic near3 wave with filter and packag$3 and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid)	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/18 16:04
L8	9	surface near3 wave with filter and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess)	US-PGPUB; USOCR; EPO; JPO	OR	ON	2006/01/18 16:09
L9	5	surface near3 wave with filter and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:10
L10	500	"29"/$.ccls. and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:10
L11	173	"29"/$.ccls. and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:13

L12	93	"361"/$.ccls. and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat$3 dividing) not 11	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:15
L13	115	"438"/$.ccls. and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat$3 dividing) not 11 not 12	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:19
L14	139	"257"/$.ccls. and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid plate) and (dummy relief vent$3 excess exceed$3) near5 (opening cavity window hole trench slot groove pocket recess) and (dicing cutting singulat$3 dividing) not 11 not 12 not 13	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 16:19
S1	1	masuko.in. and packaged.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/06 16:10
S2	3976	(base$1board substrate board base plate) with (opening cavity window) same resin with (cover covering lid)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:13
S3	912	(base$1board substrate board base plate) with (opening cavity window) with (ic chip semiconductor element device) same resin with (cover covering lid)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:21
S4	46	"29"/$.ccls. and S3	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:49
S5	82	S3 and (dicing cutting singulat$3 dividing) with (plurality individual single)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:17
S6	9	(base$1board substrate board base plate) with (opening cavity window) with (ic chip semiconductor element device) same resin with (cover covering lid) and (dicing cutting singulat$3 dividing) and saw near3 (chip ic filter device)	US-PGPUB; USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:24

S7	7	("20020044030" | "5564181" | "5699027" | "5763824" | "6204454" | "6349870" | "6467139").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:23
S8	19	(base$1board substrate board base plate) with (opening cavity window hole) with (ic chip semiconductor element device) same resin with (cover covering sheet lid) and (dicing cutting singulat$3 dividing) and hermetical$3 with (seal$4 cover$3)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:29
S9	2578	(base$1board substrate board base plate) with (opening cavity window hole groove pocket) with (ic chip semiconductor element device) and (insulat$3 dielectric resin) with (cover covering sheet lid) and (dicing cutting singulat$3 dividing) and seal$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:07
S10	197	"29"/$.ccls. and S9	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/06 16:49
S11	16	("20020092162" | "20020173074" | "4504435" | "5998243" | "6081997" | "6087202" | "6173490" | "6200121" | "6262490" | "6323064" | "6338813" | "6383846" | "6413801" | "6462421" | "6465277" | "6519844").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/06 16:51
S12	9	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (acoustic near2 wave) same (cover covering sheet lid) and (dicing cutting singulat$3 dividing) and seal$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:23
S13	59	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (acoustic near2 wave) same (cover covering sheet lid) not S12	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:18
S14	110	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (acoustic near2 wave) same (cover covering sheet lid) not S13	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:19

S15	26	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (acoustic near2 wave) same (insulat$3 dielectric resin$4) with (cover covering sheet lid) and seal$4	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:26
S16	34	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) same (insulat$3 dielectric resin$4) with (cover covering sheet lid) and seal$4 same (acoustic near2 wave)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:28
S17	35	"438"/$ and (base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) and (insulat$3 dielectric resin$4) with (cover covering sheet lid) and seal$4 and (acoustic near2 wave)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:31
S18	461	"438"/$ and (base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor) and (insulat$3 dielectric resin$4) with (cover covering sheet cap lid) and seal$4 and (dicing cutting singulat$3 dividing) not S17	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:42
S19	315	S18 and (array row column)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:35
S20	193	(base$1board substrate base$1plate board base plate) with (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4) near5 (cover covering sheet cap lid) same (opening cavity window hole trench slot groove pocket) and seal$4 same (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 17:59

S21	74	"29"/$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal$4 and (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:03
S22	65	"361"/$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal$4 and (dicing cutting singulat$3 dividing) not S21	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:05
S23	168	"438"/$.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip · semiconductor electronic component) and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal$4 and (dicing cutting singulat$3 dividing) not S21 not S22	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:28
S24	97	(opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) with (opening cavity window hole trench slot groove pocket) and seal$4 same (dicing cutting singulat$3 dividing) and (opening cavity window hole trench slot groove pocket) near5 (surround around circle encircle enclose inclose encompass ring)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:20
S25	22	(opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and seal$4 same (dicing cutting singulat$3 dividing) and surface near4 wave	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:35

S26	6	("5484647" | "5969461" | "6038133" | "6300686" | "6310421" | "6467139").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:21
S27	1	"6417574".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/17 18:34
S28	4	("5699027" | "5925931" | "5956606" | "6137380").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:27
S29	51	("5699027").URPN.	USPAT	OR	ON	2006/01/17 18:27
S30	1	"2001110946"	US-PGPUB; USPAT; EPO; JPO	OR	ON	2006/01/17 18:34
S31	27	(opening cavity window hole trench slot groove pocket) same (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and seal$4 same (dicing cutting singulat$3 dividing) and surface near4 wave	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:38
S32	16	S31 not S25	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:36
S33	5	("5459368" | "5821665" | "6078123" | "6262513" | "6310421").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:36
S34	305	(opening cavity window hole trench slot groove pocket) same (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and surface near4 wave and (seal$4 encapsluat$3) not S31	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/17 18:39
S35	9	("4474685" | "4883730" | "5394304" | "5696196" | "5703761" | "5918152" | "5968600" | "6046652" | "6218610").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/17 18:41
S36	334	"438"/106-112.ccls. and (opening cavity window hole trench slot groove pocket) with (ic chip semiconductor electronic component) and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:43
S37	17	"438"/$.ccls. and acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:47

S38	19	"333"/$.ccls. and acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing)	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:57
S39	6	("5459368" | "5699027" | "5920142" | "5991989" | "6078123" | "6078229").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:49
S40	18	("20010001740" | "20010049159" | "20020014687" | "4778326" | "5144709" | "5612513" | "5776798" | "5801074" | "5869353" | "5923958" | "6004833" | "6222738" | "6242284" | "6284569" | "6384472" | "6428650" | "6470594" | "6474477").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:51
S41	20	("5612513").URPN.	USPAT	OR	ON	2006/01/18 10:54
S42	11	("4218701" | "4502903" | "4621035" | "4814943" | "5336931" | "5350645" | "5362652" | "5389738" | "5422514" | "5477047" | "5536466").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 10:56
S43	31	"257"/$.ccls. and acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing) not S37 not S38	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 10:59
S44	13	"29"/$.ccls. and acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing) not S37 not S38 not S43	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 11:00
S45	1	"361"/$.ccls. and acoustic near2 wave and (insulat$3 dielectric resin$4 non$1conducti$2) near5 (cover covering sheet cap lid) and (dicing cutting singulat$3 dividing) not S37 not S38 not S43	USPAT; USOCR; EPO; JPO	OR	ON	2006/01/18 14:28
S46	3	("5403783" | "5471027" | "5744863").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/18 11:01
S47	12	("5923958").URPN.	USPAT	OR	ON	2006/01/18 11:01